

Title (en)

NEW ENAMEL-DENTIN ADHESIVES BASED ON CHEMICALLY MODIFIED NATURAL POLYSACCHARIDES

Title (de)

NEUE ZAHNSCHMELZKLEBSTOFFE AUS CHEMISCH MODIFIZIERTEN NATÜRLICHEN POLYSACCHARIDEN

Title (fr)

ADHÉSIFS NOUVEAUX POUR DENTINE À BASE DE POLYSACCHARIDES NATURELS MODIFIÉS

Publication

**EP 3110852 A1 20170104 (EN)**

Application

**EP 15712063 A 20150226**

Priority

- IT PD20140043 A 20140227
- EP 2015054014 W 20150226

Abstract (en)

[origin: WO2015128415A1] The present invention concerns the preparation of chemically modified derivatives of chitosan with acrylic groups and their use in the field of enamel-dentin adhesives. Chitosan derivatives have physical-chemical features (hydrophilicity, presence of electrical charges on the chain) which allow them to interact with the organic part of the demineralized tooth. At the same time, the acrylic groups incorporated in the polymer chain allow the formation of a covalent bond with the restorative material used in the dental field that is typically composed of acrylic resins. By combining the adhesion to the tooth surface and the bond with the restorative material, the chemically modified chitosan described herein is able to increase the lifespan of the dental restoration and can thus find use in the field of adhesives, in particular enamel-dentin adhesives.

IPC 8 full level

**C08B 37/08** (2006.01); **A61K 6/898** (2020.01); **A61L 24/08** (2006.01)

CPC (source: EP US)

**A61K 6/887** (2020.01 - EP US); **A61K 6/898** (2020.01 - EP US); **A61L 24/08** (2013.01 - EP US); **C08B 37/003** (2013.01 - EP US)

Citation (search report)

See references of WO 2015128415A1

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